

Title (en)

POTTING COMPOUND, METHOD FOR ELECTRICALLY ISOLATING AN ELECTRICAL OR ELECTRONIC COMPONENT, AND ELECTRICALLY ISOLATED COMPONENT

Title (de)

VERGUSMASSE, VERFAHREN ZUM ELEKTRISCHEN ISOLIEREN EINES ELEKTRISCHEN ODER ELEKTRONISCHEN BAUTEILS UND ELEKTRISCH ISOLIERTES BAUTEIL

Title (fr)

MATÉRIAU D'ENROBAGE, PROCÉDÉ D'ISOLATION ÉLECTRIQUE D'UN COMPOSANT ÉLECTRIQUE OU ÉLECTRONIQUE ET COMPOSANT ISOLÉ ÉLECTRIQUEMENT

Publication

EP 3844808 A1 20210707 (DE)

Application

EP 19745089 A 20190723

Priority

- DE 102018214641 A 20180829
- EP 2019069757 W 20190723

Abstract (en)

[origin: WO2020043395A1] The invention relates to a potting compound. Said potting compound contains 5.0-30.0 wt.% reactive particles, selected from magnesium oxide particles with a maximum particle size of 5.0 µm, porous magnesium oxide particle agglomerates, silicon oxide particles with a maximum particle size of 0.5 µm, silica particles with a maximum particle size of 0.5 µm and mixtures thereof, 45.0-90.0 wt.% filler particles with a particle size exceeding 1 µm and/or filler fibres, and 5.0-20.0 wt.% water. The component is potted using the potting compound (11) in a method for electrically isolating an electrical or electronic component. Said component is then heat-treated at a temperature ranging from 50°C to 95°C in an atmosphere saturated with water (12) and dried. An electrically isolated component can be produced in this way.

IPC 8 full level

H01L 23/29 (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP KR)

H01L 23/291 (2013.01 - EP KR); **H01L 23/3135** (2013.01 - EP KR)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2020043395 A1 20200305; CN 112585747 A 20210330; DE 102018214641 A1 20200305; DE 102018214641 B4 20220922; EP 3844808 A1 20210707; JP 2021536128 A 20211223; JP 7271656 B2 20230511; KR 102648484 B1 20240319; KR 20210047876 A 20210430; TW 202020100 A 20200601; TW I827655 B 20240101

DOCDB simple family (application)

EP 2019069757 W 20190723; CN 201980055969 A 20190723; DE 102018214641 A 20180829; EP 19745089 A 20190723; JP 2021510739 A 20190723; KR 20217005360 A 20190723; TW 108130815 A 20190828